



Material Content Data Sheet



Sales Product Name		BSF450NE7NH3		Issued		26. September 2017		
MA#		MA001389732						
Package		MG-WDSON-2-1		Weight*		49.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.774	3.56	3.56	35580	35580
leadframe	non noble metal	copper	7440-50-8	45.429	91.11	91.11	911044	911044
leadfinish	non noble metal	nickel	7440-02-0	0.121	0.24		2429	
	noble metal	silver	7440-22-4	0.482	0.97	1.21	9663	12092
plating	non noble metal	nickel	7440-02-0	0.121	0.24	0.24	2429	2429
glue	plastics	epoxy resin	-	0.107	0.21		2142	
	noble metal	silver	7440-22-4	0.656	1.32	1.53	13160	15302
solder	non noble metal	copper	7440-50-8	0.005	0.01		107	
	noble metal	silver	7440-22-4	0.032	0.06		641	
	non noble metal	tin	7440-31-5	1.028	2.06	2.13	20606	21354
passivation	plastics	epoxy resin	-	0.110	0.22	0.22	2199	2199
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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